

Press release

mechatronic systemtechnik gmbh presents new Wafer Handling Systems RR200/300 and FPT150/200

(Villach, February 8, 2011) Carinthia-based mechatronic systemtechnik gmbh manufacturer of thin-wafer handling systems recently came out with two newly developed stand-alone systems: Ring Remover RR200/300 and Frame Packing Tool FPT150/200

For the first time, the Ring Remover RR200/300 enables fully automated removal of rings from laminated 200mm (8") and 300mm (12") wafers. "Whereas earlier the rings had to be manually separated with big effort, the RR200/300 enables automated removal with a throughput of 80 wafers per hour", stated Walter Schober, CEO of mechatronic systemtechnik gmbh. The handling system features a dual cassette platform with an automatic cassette detection device and a mapper for detection of quantity, position and possible misalignment of a wafer frame in the cassette. Additionally, the RR200/300 is fitted with a contact-free optoelectronic eccentricity detector for wafer frames and an OCR unit for bar codes. The new system fulfils guidelines for usage in cleanroom ISO class 5 (former class 100 according to Federal Standard 209E) and is compliant with CE specifications.

The new Frame Packing Tool FPT150/200 is a high-performance fully automatic machine for transfer of 150mm (6") and 200mm (8") wafer frames between cassettes and shipping boxes. "Thanks to its neat front-mounted operations panel, the machine footprint is reduced by 65 percent. This has resulted in a distinctly more efficient space utilisation of expensive area of cleanrooms by up to ISO class 4 (former class 10)", Schober declared. "Whereas the machines of competitors process a mere 150 frames per hour, our new development permits to double the throughput", Schober further stated. For this purpose, the FPT150/200 is fitted with a high-performance, multi-axis robot arm and two independent loading stations. Operation of the machine is through an intuitive and ergonomic user interface on a modern 19" touch screen with optional keyboard. Movement programming is tailored for respective requirements of the handling processes so as to achieve a maximum on output from the FPT150/200.

"Both the new systems are the innovative extension of our product portfolio and take increased customer demands into account", concluded Schober.



Ring Remover RR200/300



Frame Packing Tool FPT150/200

About mechatronic systemtechnik gmbh

mechatronic systemtechnik gmbh based in Villach (Austria) develops, manufactures and markets special-purpose machines for the semiconductor industry since 1998 and has a world-wide unique product portfolio for handling of silicone thin-wafers. Discs made from semiconductor material find application above all in the growing market of entertainment electronics, e.g. mobile phones, MP3 players, digital cameras or camcorders. With their patented thin wafer handling systems, mechatronic systemtechnik has a unique selling proposition in the international market. mechatronic systemtechnik handling-systems transport wafers contactless and 100 percent automatic. Various processes and instruments have been developed for this purpose. Depending upon customer requirements, these can be installed, e.g. Bernoulli (Vacuum) Technology. This gives a minimum technological lead of four years. Leading international companies such as Infineon, NXP, Nikon, Rudolph, TSMC, UMC, ASE, STATS ChipPAC, ... are amongst the customers.

Contact:

*Martina Lintner
Public Relations
mechatronic systemtechnik gmbh
Tiroler Straße 80
A-9500 Villach
Tel.: +43-(0)4242-33999-0
E-Mail: martina.lintner@mechatronic.at
Internet: www.mechatronic.at*